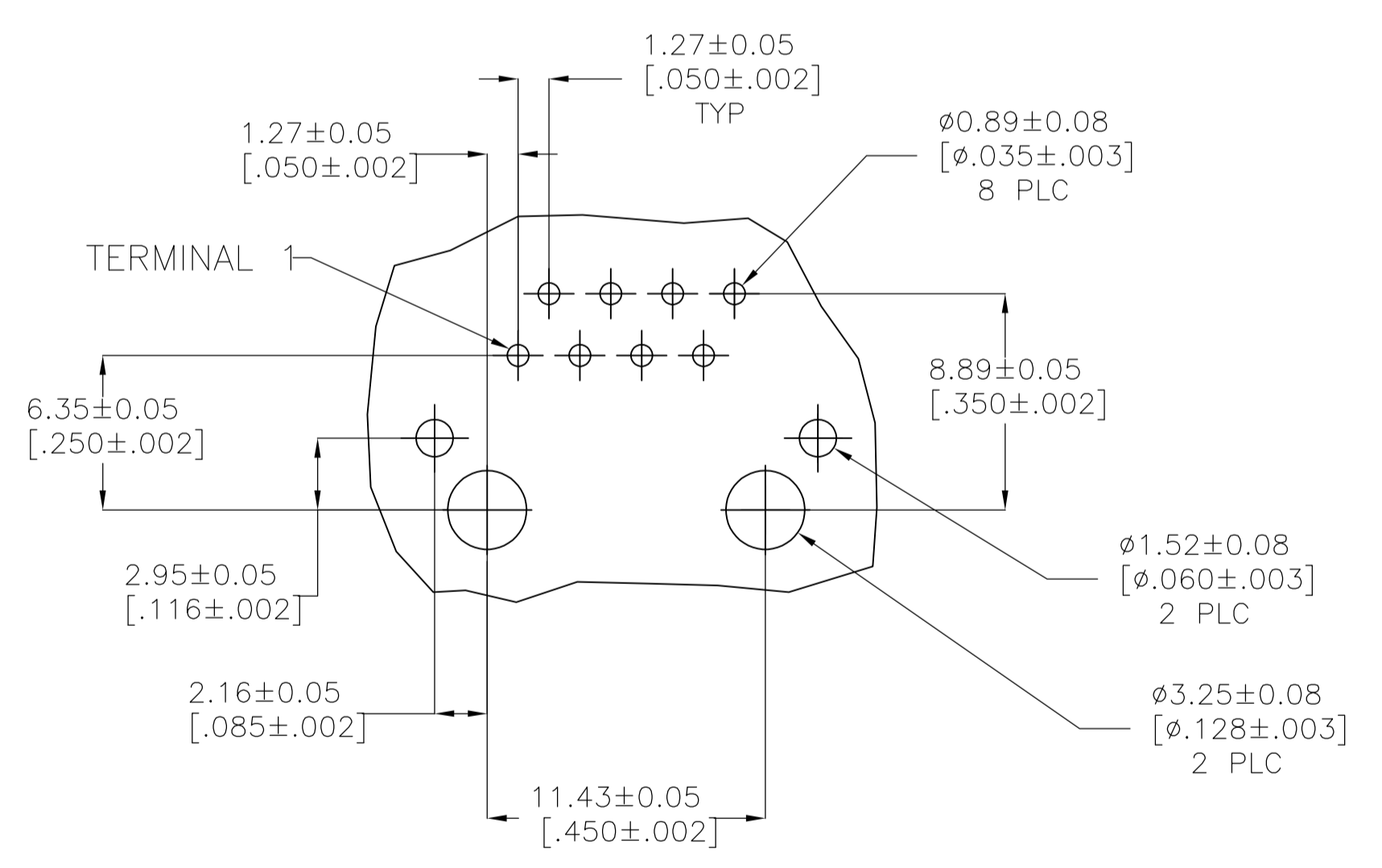
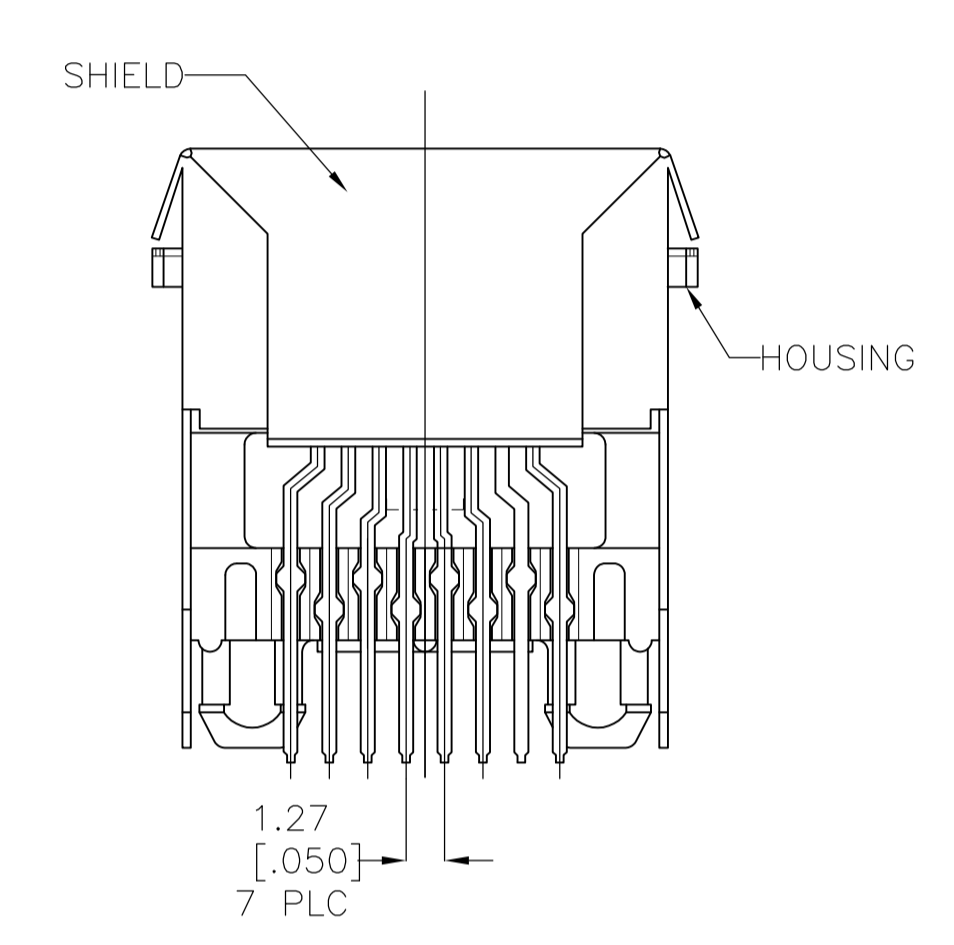
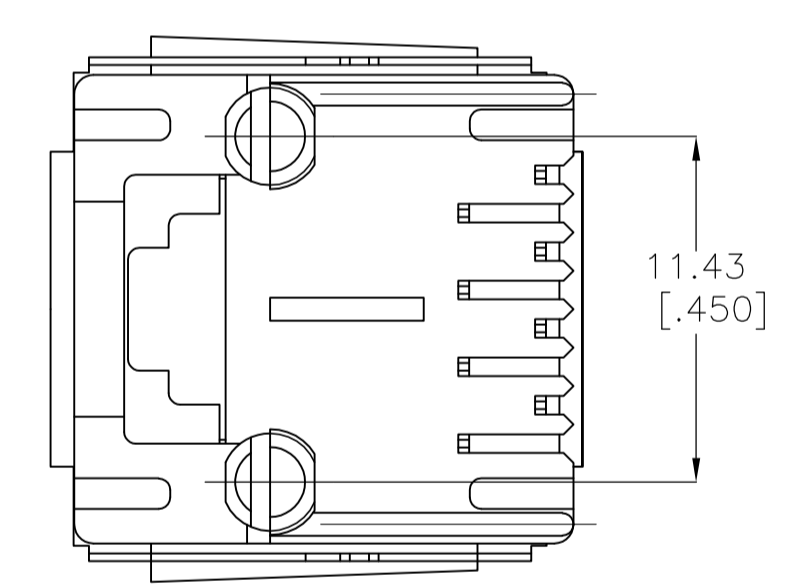
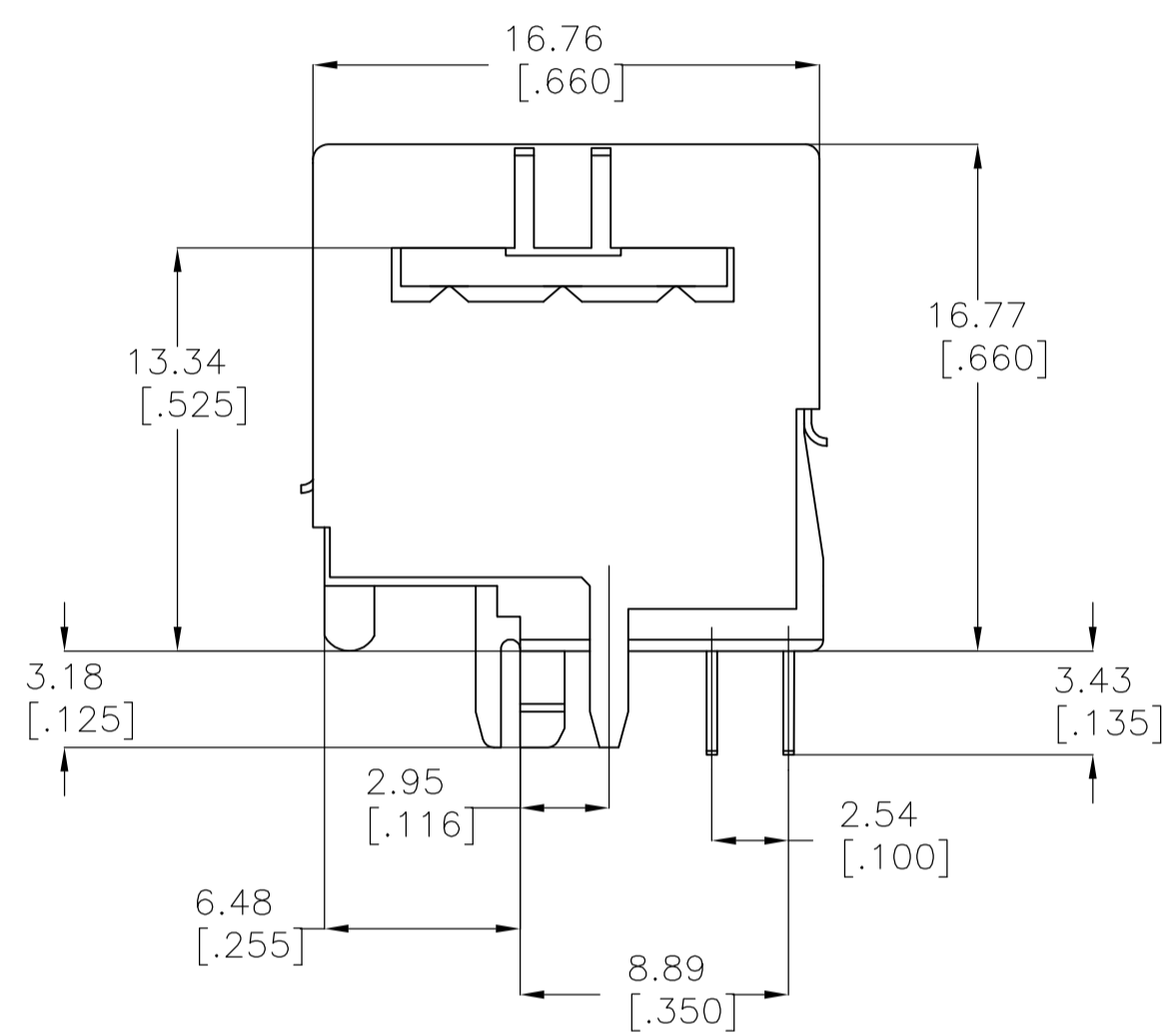
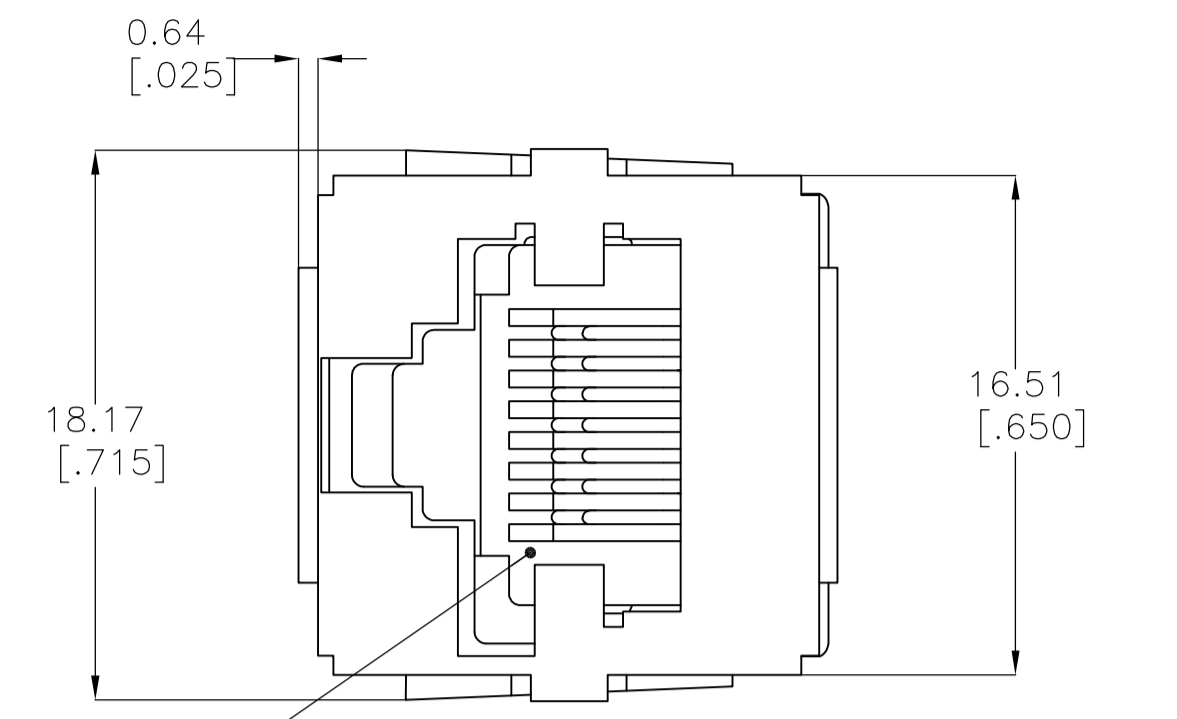
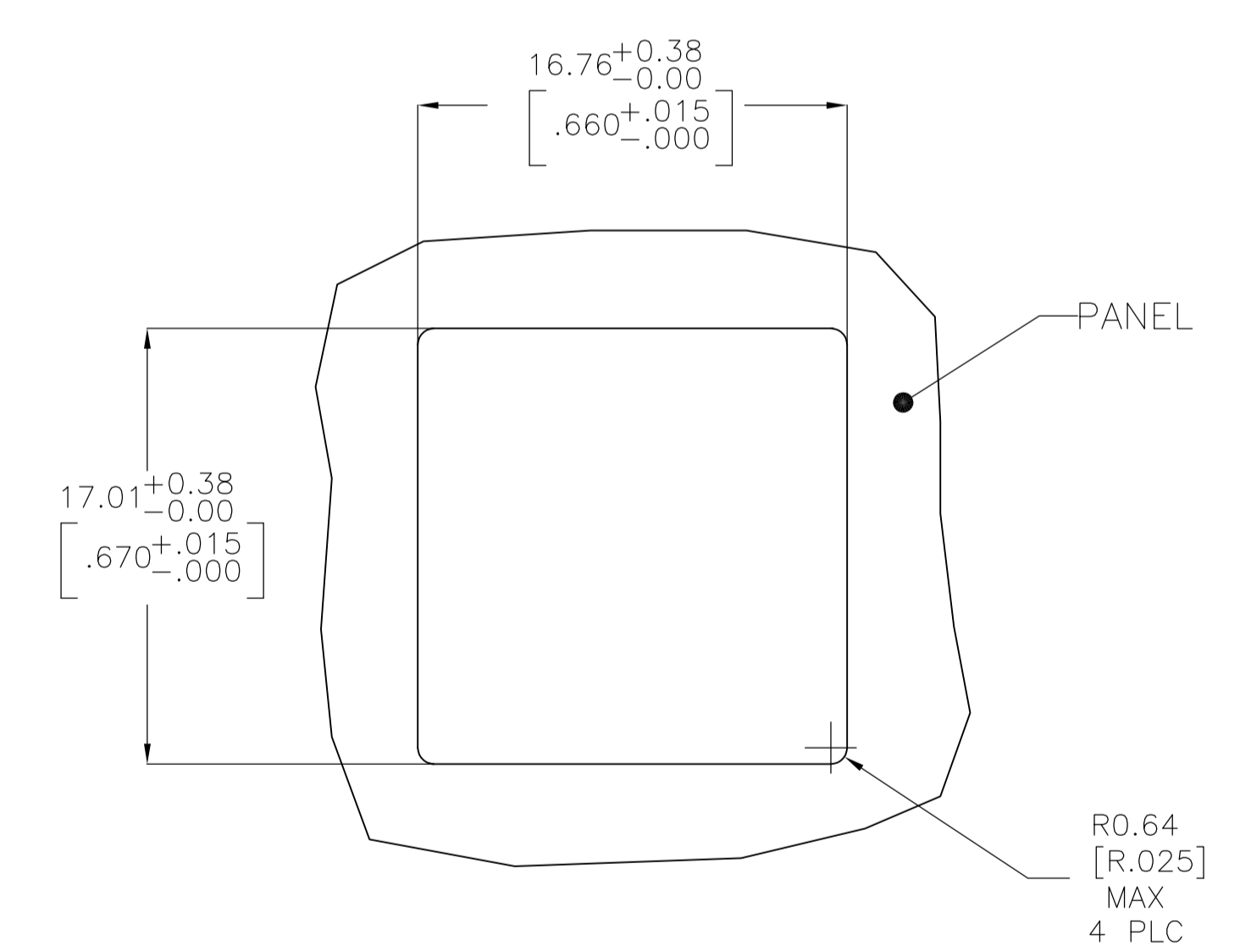


LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DMN	APVD		
B		ECO-07-021363	25SEPT07	LAM	PR		



RECOMMENDED PRINTED
 CIRCUIT BOARD LAYOUT
 COMPONENT SIDE SHOWN



RECOMMENDED PANEL
 CUTOUT

- MATERIAL:
 HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
 TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81μm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MIN THICK NICKEL UNDERPLATE
 SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0μm [.000120] MIN THICK REFLOWED TIN.

2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

1888412-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN D. STRAUSSER/07MAR2006		Tyco Electronics Corporation	
DIMENSIONS: mm [INCHES]		CHK J.WESTMAN/07MAR2006		Harrisburg, PA 17105-3608	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S.FLICKINGER/07MAR2006		NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS	
0 PLC ± -	1 PLC ± -	PRODUCT SPEC	108-1163	SIZE	A1
2 PLC ± -	3 PLC ± 0.13(.005)	APPLICATION SPEC	114-2048	CAGE CODE	00779
4 PLC ± -	ANGLES ± -	WEIGHT	-	DRAWING NO	1888412
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	CUSTOMER DRAWING	SCALE	4:1	SHEET 1 OF 1